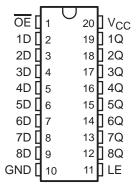
SCBS773 - NOVEMBER 2003

- Controlled Baseline
 - One Assembly/Test Site, One Fabrication Site
- Enhanced Diminishing Manufacturing Sources (DMS) Support
- Enhanced Product-Change Notification
- Qualification Pedigree[†]
- Supports Mixed-Mode Signal Operation (5-V Input and Output Voltages With 3.3-V V_{CC})
- Supports Unregulated Battery Operation Down To 2.7 V
- Typical V_{OLP} (Output Ground Bounce)
 <0.8 V at V_{CC} = 3.3 V, T_A = 25°C
- I_{off} and Power-Up 3-State Support Hot Insertion
- † Component qualification in accordance with JEDEC and industry standards to ensure reliable operation over an extended temperature range. This includes, but is not limited to, Highly Accelerated Stress Test (HAST) or biased 85/85, temperature cycle, autoclave or unbiased HAST, electromigration, bond intermetallic life, and mold compound life. Such qualification testing should not be viewed as justifying use of this component beyond specified performance and environmental limits.

- Bus Hold on Data Inputs Eliminates the Need for External Pullup/Pulldown Resistors
- Latch-Up Performance Exceeds 500 mA Per JESD 17
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)

PW PACKAGE (TOP VIEW)



description/ordering information

This octal latch is designed specifically for low-voltage (3.3-V) V_{CC} operation, but with the capability to provide a TTL interface to a 5-V system environment.

The eight latches of the SN74LVTH573 are transparent D-type latches. While the latch-enable (LE) input is high, the Q outputs follow the data (D) inputs. When LE is taken low, the Q outputs are latched at the logic levels set up at the D inputs.

A buffered output-enable (\overline{OE}) input can be used to place the eight outputs in either a normal logic state (high or low logic levels) or a high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and increased drive provide the capability to drive bus lines without need for interface or pullup components.

OE does not affect the internal operations of the latches. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

ORDERING INFORMATION

TA	PACKA	GE‡	ORDERABLE PART NUMBER	TOP-SIDE MARKING
-40°C to 85°C	TSSOP - PW	Tape and reel	SN74LVTH573IPWREP	LH573EP

[‡] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



SCBS773 - NOVEMBER 2003

description/ordering information

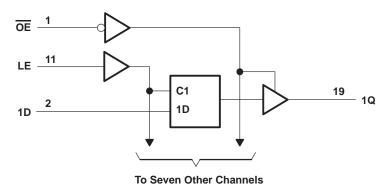
Active bus-hold circuitry is provided to hold unused or floating data inputs at a valid logic level. Use of pullup or pulldown resistors with the bus-hold circuitry is not recommended.

This device is fully specified for hot-insertion applications using I_{off} and power-up 3-state. The I_{off} circuitry disables the outputs, preventing damaging current backflow through the devices when they are powered down. The power-up 3-state circuitry places the outputs in the high-impedance state during power up and power down, which prevents driver conflict.

FUNCTION TABLE (each latch)

	INPUTS		OUTPUT
OE	LE	D	Q
L	Н	Н	Н
L	Н	L	L
L	L	Χ	Q_0
Н	X	Χ	Z

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}	0.5 V to 4.6 V
Input voltage range, V _I (see Note 1)	–0.5 V to 7 V
Voltage range applied to any output in the high-impedance	
or power-off state, V _O (see Note 1)	–0.5 V to 7 V
Voltage range applied to any output in the high state, VO (see Note 1)	\dots -0.5 V to V _{CC} + 0.5 V
Current into any output in the low state, I _O	128 mA
Current into any output in the high state, I _O (see Note 2)	64 mA
Input clamp current, I _{IK} (V _I < 0)	–50 mA
Output clamp current, I _{OK} (V _O < 0)	–50 mA
Package thermal impedance, θ _{JA} (see Note 3)	83°C/W
Storage temperature range, T _{stg}	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

- 2. This current flows only when the output is in the high state and $V_O > V_{CC}$.
- 3. The package thermal impedance is calculated in accordance with JESD 51-7.



SN74LVTH573-EP 3.3-V ABT OCTAL TRANSPARENT D-TYPE LATCH WITH 3-STATE OUTPUTS

SCBS773 - NOVEMBER 2003

recommended operating conditions (see Note 4)

			MIN	MAX	UNIT
Vcc	Supply voltage		2.7	3.6	V
V _{IH}	High-level input voltage		2		V
V _{IL}	Low-level input voltage			8.0	V
VI	Input voltage			5.5	V
IOH	High-level output current			-32	mA
loL	Low-level output current			64	mA
Δt/Δν	Input transition rise or fall rate	Outputs enabled		10	ns/V
Δt/ΔV _{CC}	Power-up ramp rate		200		μs/V
TA	Operating free-air temperature		-40	85	°C

NOTE 4: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PAI	RAMETER	TEST CONDITIO	NS	MIN TYPT	MAX	UNIT	
VIK		V _{CC} = 2.7 V,	I _I = -18 mA		-1.2	V	
		$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V},$	I _{OH} = -100 μA	V _{CC} -0.2			
Voн		V _{CC} = 2.7 V,	IOH = -8 mA	2.4		V	
		V _{CC} = 3 V,	$I_{OH} = -32 \text{ mA}$	2			
		V 27V	I _{OL} = 100 μA		0.2		
		V _{CC} = 2.7 V	$I_{OL} = 24 \text{ mA}$		0.5		
VOL			$I_{OL} = 16 \text{ mA}$		0.4	V	
		V _{CC} = 3 V	$I_{OL} = 32 \text{ mA}$		0.5		
			$I_{OL} = 64 \text{ mA}$		0.55		
İ	Control innuito	V _{CC} = 0 or 3.6 V,	$V_{I} = 5.5 V$		10		
6.	Control inputs	V _{CC} = 3.6 V,	$V_I = V_{CC}$ or GND		±1	^	
1 ₁	Data innuta	V 26V	VI = VCC		1	μΑ	
	Data inputs	V _C C = 3.6 V	V _I = 0		-5		
I _{off}		$V_{CC} = 0$,	V_I or $V_O = 0$ to 4.5 V		±100	μΑ	
		V 2V	$V_{I} = 0.8 V$	75			
ll(hold)	Data inputs	VCC = 3 V	V _I = 2 V	-75		μΑ	
		$V_{CC} = 3.6 V^{\ddagger},$	$V_{I} = 0 \text{ to } 3.6 \text{ V}$		±500		
I _{OZH}		$V_{CC} = 3.6 \text{ V},$	V _O = 3 V		5	μΑ	
lozL		$V_{CC} = 3.6 \text{ V},$	$V_0 = 0.5 V$		-5	μΑ	
lozpu		$V_{CC} = 0 \text{ to } 1.5 \text{ V}, V_{O} = 0.5 \text{ V to } 3 \text{ V}, \overline{OE} = \text{do}$	on't care		±100	μΑ	
lozpd		$V_{CC} = 1.5 \text{ V to } 0, V_{O} = 0.5 \text{ V to } 3 \text{ V}, \overline{OE} = do$	on't care		±100	μА	
		Outputs high			0.19		
ICC		$V_{CC} = 3.6 \text{ V}, I_{O} = 0, V_{I} = V_{CC} \text{ or GND}$	Outputs low	5		mA	
			Outputs disabled		0.19		
ΔICC§		$V_{CC} = 3 \text{ V to } 3.6 \text{ V}$, One input at $V_{CC} - 0.6 \text{ V}$	V _{CC} = 3 V to 3.6 V, One input at V _{CC} – 0.6 V, Other inputs at V _{CC} or GND				
Ci		V _I = 3 V or 0	V _I = 3 V or 0				
Co		V _O = 3 V or 0		7		pF	

 $^{^{\}dagger}_{\cdot}$ All typical values are at V_{CC} = 3.3 V, T_A = 25°C.

[§] This is the increase in supply current for each input that is at the specified TTL voltage level, rather than VCC or GND.



[‡] This is the bus-hold maximum dynamic current. It is the minimum overdrive current required to switch the input from one state to another.

SN74LVTH573-EP 3.3-V ABT OCTAL TRANSPARENT D-TYPE LATCH WITH 3-STATE OUTPUTS

SCBS773 - NOVEMBER 2003

timing requirements over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

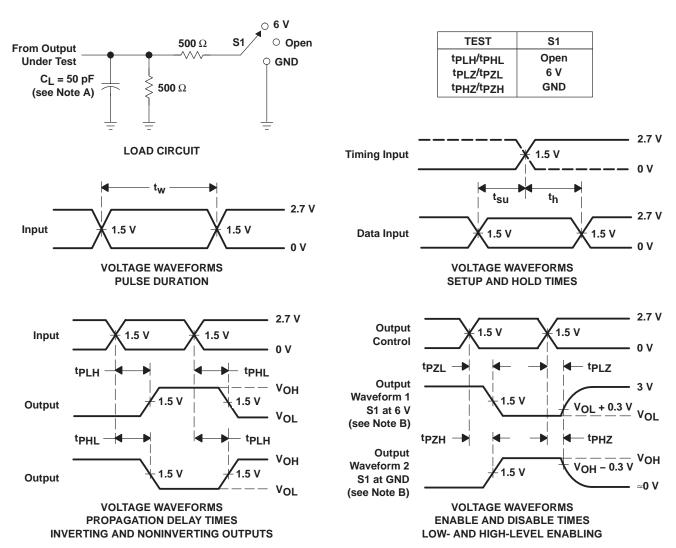
		V _{CC} =	3.3 V 3 V	VCC =	UNIT	
		MIN	MAX	MIN	MAX	
t _W	Pulse duration, LE high	3		3		ns
t _{su}	Setup time, data before LE↓	0.7		0.6		ns
th	Hold time, data after LE↓	1.5		1.7		ns

switching characteristics over recommended free-air temperature, $C_L = 50$ pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM					VCC =	UNIT	
	(INPUT)	(OUTPUT)	MIN	TYP [†]	MAX	MIN	MAX	
^t PLH	6		1.5	2.6	3.9		4.5	
^t PHL	D	Q	1.5	2.9	3.9		4.5	ns
^t PLH			1.9	2.9	4.2		4.9	
^t PHL	LE	Q	1.9	2.9	4.2		4.9	ns
^t PZH	ŌĒ	•	1.5	3.2	5.1		5.9	
^t PZL	OE .	Q	1.5	3.9	5.1		5.9	ns
^t PHZ		•	2	3.5	4.9		5.5	
^t PLZ	ŌĒ	Q	2	3.2	4.6		4.9	ns

[†] All typical values are at $V_{CC} = 3.3 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_Q = 50 \ \Omega$, $t_f \leq 2.5 \ ns$.
- D. The outputs are measured one at a time with one transition per measurement.
- E. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms



PACKAGE OPTION ADDENDUM

10-Dec-2020

PACKAGING INFORMATION

www.ti.com

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
SN74LVTH573IPWREP	ACTIVE	TSSOP	PW	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LH573EP	Samples
V62/04678-01XE	ACTIVE	TSSOP	PW	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LH573EP	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.



PACKAGE OPTION ADDENDUM

10-Dec-2020

OTHER QUALIFIED VERSIONS OF SN74LVTH573-EP:

◆ Catalog: SN74LVTH573

• Military: SN54LVTH573

NOTE: Qualified Version Definitions:

• Catalog - TI's standard catalog product

• Military - QML certified for Military and Defense Applications

PACKAGE MATERIALS INFORMATION

www.ti.com 3-Jun-2022

TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LVTH573IPWREI	TSSOP	PW	20	2000	330.0	16.4	6.95	7.1	1.6	8.0	16.0	Q1

PACKAGE MATERIALS INFORMATION

www.ti.com 3-Jun-2022



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LVTH573IPWREP	TSSOP	PW	20	2000	356.0	356.0	35.0

IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATA SHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, regulatory or other requirements.

These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to TI's Terms of Sale or other applicable terms available either on ti.com or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products.

TI objects to and rejects any additional or different terms you may have proposed.

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265 Copyright © 2022, Texas Instruments Incorporated